Renesas Electronics America Inc - R5F2LA86ANFP#V0 Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	72
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2la86anfp-v0

Table 1.2 Programmable I/O Ports Provided for Each Group (R8C/LA3A Group, R8C/LA5A Group)

Programmable I/O Port	R8C/LA3A Group Total: 26 I/O pins								R8C/LA5A Group Total: 44 I/O pins							
	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P0	—	—	—	—	—	—	—	—	✓	✓	✓	✓	✓	✓	✓	✓
P2	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P3	—	—	—	—	—	—	—	—	✓	✓	✓	✓	✓	✓	✓	✓
P5	—	✓	✓	✓	✓	✓	✓	✓	—	✓	✓	✓	✓	✓	✓	✓
P7	—	—	—	—	—	—	✓	—	—	—	—	—	—	✓	✓	✓
P8	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P9	—	—	—	—	—	—	✓	✓	—	—	—	—	—	—	✓	✓

Notes:
1. The symbol "✓" indicates a programmable I/O port.
2. The symbol "—" indicates the settings should be made as follows:
   - Set 0 to the corresponding bits in the PDi (i = 0, 3, 5, 7, 9) register. When read, the content is 0.
   - Set 0 to the corresponding bits in the Pi (i = 0, 3, 5, 7, 9) register. When read, the content is 0.

Table 1.3 Programmable I/O Ports Provided for Each Group (R8C/LA6A Group, R8C/LA8A Group)

Programmable I/O Port	R8C/LA6A Group Total: 56 I/O pins								R8C/LA8A Group Total: 72 I/O pins							
	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
P0	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P1	✓	✓	✓	✓	✓	✓	—	—	✓	✓	✓	✓	✓	✓	✓	✓
P2	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P3	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P4	✓	✓	—	—	—	—	—	—	✓	✓	✓	✓	✓	✓	✓	✓
P5	—	✓	✓	✓	✓	✓	✓	✓	—	✓	✓	✓	✓	✓	✓	✓
P6	✓	✓	✓	✓	✓	✓	✓	—	✓	✓	✓	✓	✓	✓	✓	✓
P7	—	—	—	—	—	—	—	—	—	✓	✓	✓	✓	✓	✓	✓
P8	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P9	—	—	—	—	—	—	✓	✓	—	—	—	—	—	—	✓	✓

Notes:
1. The symbol "✓" indicates a programmable I/O port.
2. The symbol "—" indicates the settings should be made as follows:
   - Set 0 to the corresponding bits in the PDi (i = 1, 4 to 7, 9) register. When read, the content is 0.
   - Set 0 to the corresponding bits in the Pi (i = 1, 4 to 7, 9) register. When read, the content is 0.
   - Set 0 to the corresponding bits in the P7DRR register. When read, the content is 0.

1.1.3 Specifications

Tables 1.6 to 1.8 list the specifications.

Table 1.6 Specifications (1)

Item	Function		Specification
CPU	Central processing unit		R8C CPU core • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns (f(XIN) = 20 MHz, VCC = 2.7 V to 5.5 V) 125 ns (f(XIN) = 8 MHz, VCC = 1.8 V to 5.5 V) • Multiplier: 16 bits × 16 bits → 32 bits • Multiply-accumulate instruction: 16 bits × 16 bits + 32 bits → 32 bits • Operating mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM/RAM Data flash		Refer to Tables 1.9 to 1.12 Product Lists.
Power Supply Voltage Detection	Voltage detection circuit		• Power-on reset • Voltage detection 3 (detection level of voltage detection 0 and voltage detection 1 selectable)
I/O Ports	Programmable I/O ports	R8C/LA3A Group	• CMOS I/O ports: 26, selectable pull-up resistor (1) • High current drive ports: 8
		R8C/LA5A Group	• CMOS I/O ports: 44, selectable pull-up resistor (1) • High current drive ports: 8
		R8C/LA6A Group	• CMOS I/O ports: 56, selectable pull-up resistor (1) • High current drive ports: 8
		R8C/LA8A Group	• CMOS I/O ports: 72, selectable pull-up resistor (1) • High current drive ports: 10
Clock	Clock generation circuits		4 circuits: XIN clock oscillation circuit XCIN clock oscillation circuit (32 kHz) High-speed on-chip oscillator (with frequency adjustment function) Low-speed on-chip oscillator • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Division ratio selectable from 1, 2, 4, 8, and 16 • Low-power-consumption modes: Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode, power-off mode
			Real-time clock (timer RH)
Interrupts		R8C/LA3A Group	• Number of interrupt vectors: 69 • External Interrupt: 13 ($\overline{\text{INT}}$ × 5, key input × 8) • Priority levels: 7 levels
		R8C/LA5A Group	• Number of interrupt vectors: 69 • External Interrupt: 14 ($\overline{\text{INT}}$ × 6, key input × 8) • Priority levels: 7 levels
		R8C/LA6A Group	• Number of interrupt vectors: 69 • External Interrupt: 16 ($\overline{\text{INT}}$ × 8, key input × 8) • Priority levels: 7 levels
		R8C/LA8A Group	
Watchdog Timer			• 14 bits × 1 (with prescaler) • Selectable reset start function • Selectable low-speed on-chip oscillator for watchdog timer

Note:
1. No pull-up resistor is provided in the pins P5_4 to P5_6.

Table 1.10 Product List for R8C/LA5A Group **Current of Oct 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2LA52ANFP	8 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	N Version
R5F2LA54ANFP	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F2LA56ANFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F2LA58ANFP	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0052JA-A	
R5F2LA52ADFP	8 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	D Version
R5F2LA54ADFP	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F2LA56ADFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F2LA58ADFP	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0052JA-A	

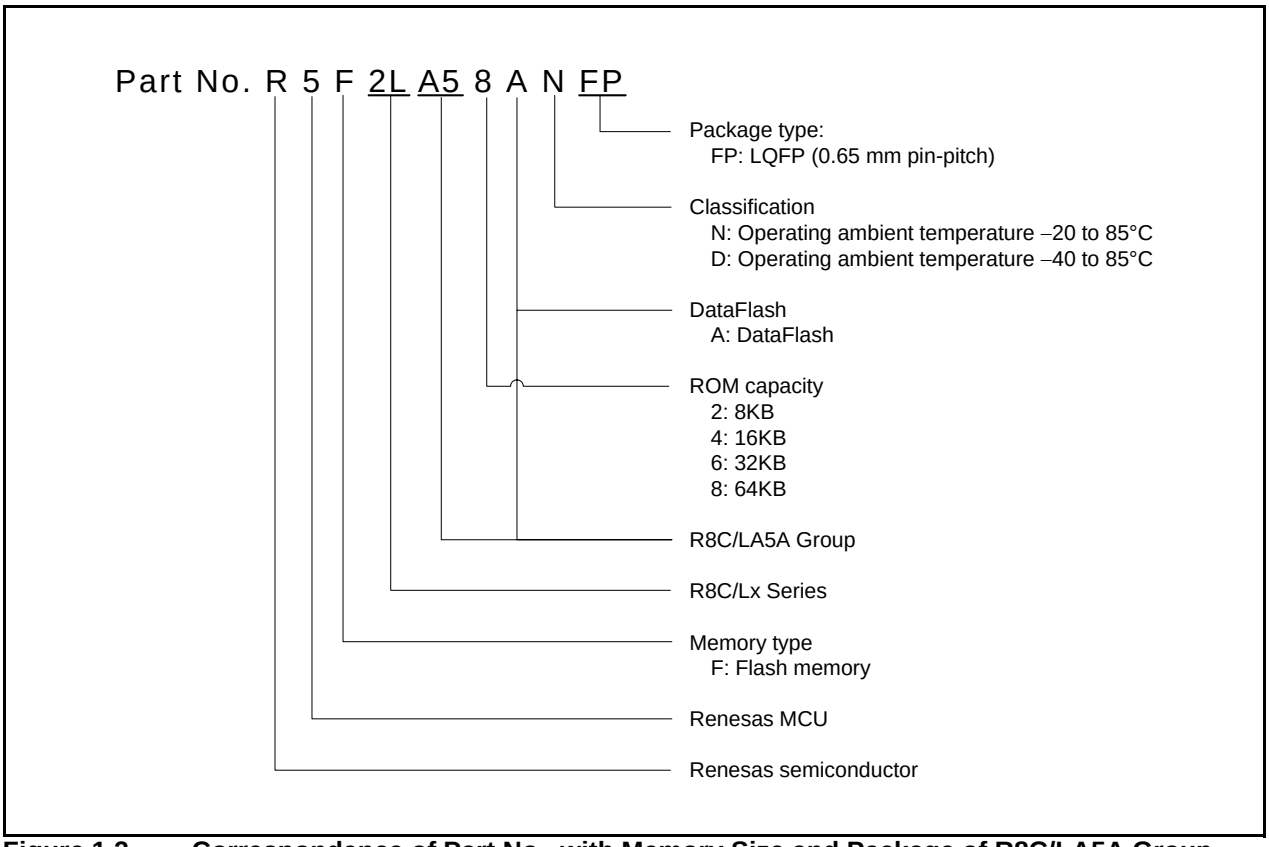


Figure 1.2 Correspondence of Part No., with Memory Size and Package of R8C/LA5A Group

Table 1.12 Product List for R8C/LA8A Group **Current of Oct 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2LA84ANFP	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0080KB-A	N Version
R5F2LA84ANFA	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0080JA-A	
R5F2LA86ANFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0080KB-A	
R5F2LA86ANFA	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0080JA-A	
R5F2LA87ANFP	48 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0080KB-A	
R5F2LA87ANFA	48 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0080JA-A	
R5F2LA88ANFP	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0080KB-A	
R5F2LA88ANFA	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0080JA-A	
R5F2LA8AANFP	96 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0080KB-A	
R5F2LA8AANFA	96 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0080JA-A	
R5F2LA8CANFP	128 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0080KB-A	
R5F2LA8CANFA	128 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0080JA-A	
R5F2LA84ADFP	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0080KB-A	D Version
R5F2LA84ADFA	16 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0080JA-A	
R5F2LA86ADFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0080KB-A	
R5F2LA86ADFA	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0080JA-A	
R5F2LA87ADFP	48 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0080KB-A	
R5F2LA87ADFA	48 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0080JA-A	
R5F2LA88ADFP	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0080KB-A	
R5F2LA88ADFA	64 Kbytes	1 Kbyte × 2	3.5 Kbytes	PLQP0080JA-A	
R5F2LA8AADFP	96 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0080KB-A	
R5F2LA8AADFA	96 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0080JA-A	
R5F2LA8CADFP	128 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0080KB-A	
R5F2LA8CADFA	128 Kbytes	2 Kbytes × 2	5.5 Kbytes	PLQP0080JA-A	

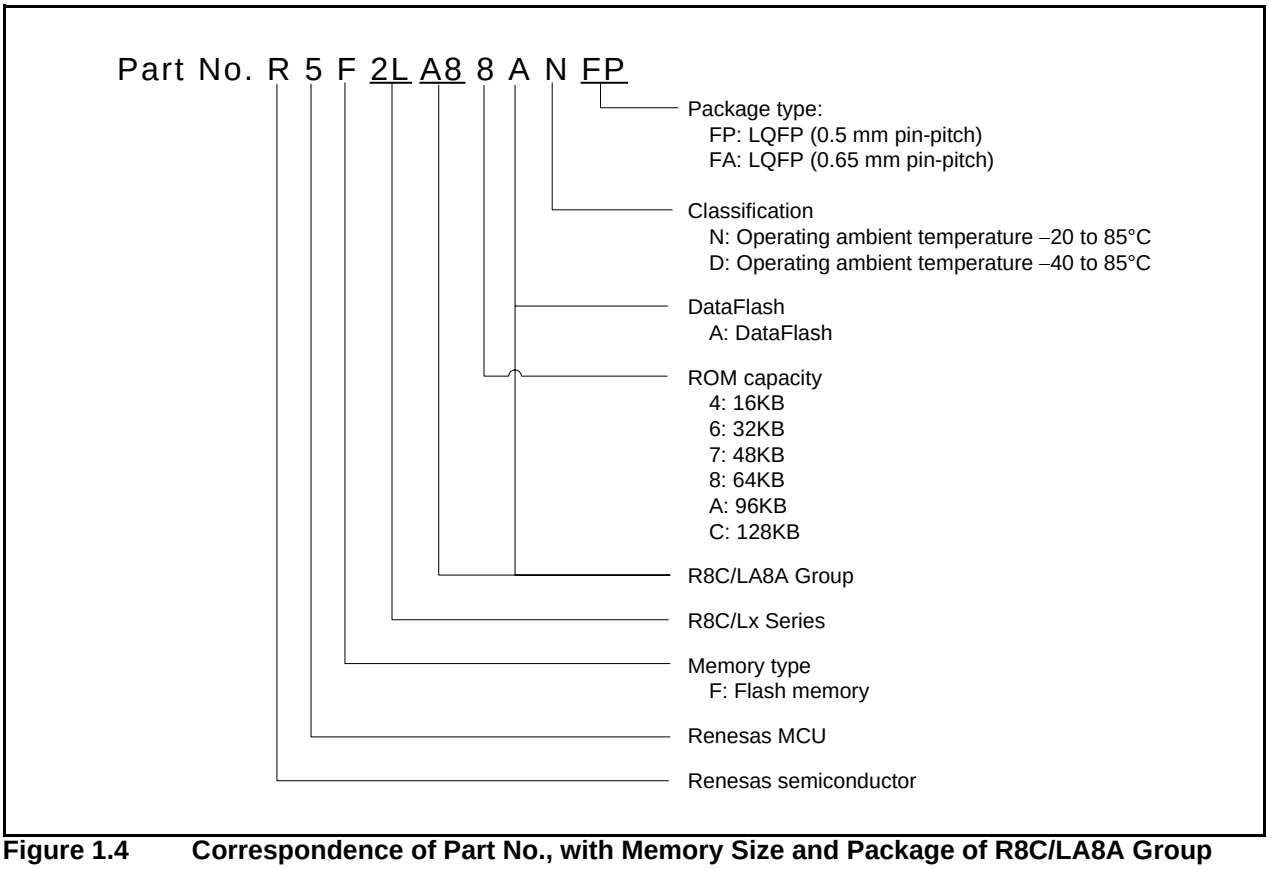


Figure 1.4 Correspondence of Part No., with Memory Size and Package of R8C/LA8A Group

1.3 Block Diagrams

Figure 1.5 shows a Block Diagram of R8C/LA3A Group. Figure 1.6 shows a Block Diagram of R8C/LA5A Group. Figure 1.7 shows a Block Diagram of R8C/LA6A Group. Figure 1.8 shows a Block Diagram of R8C/LA8A Group.

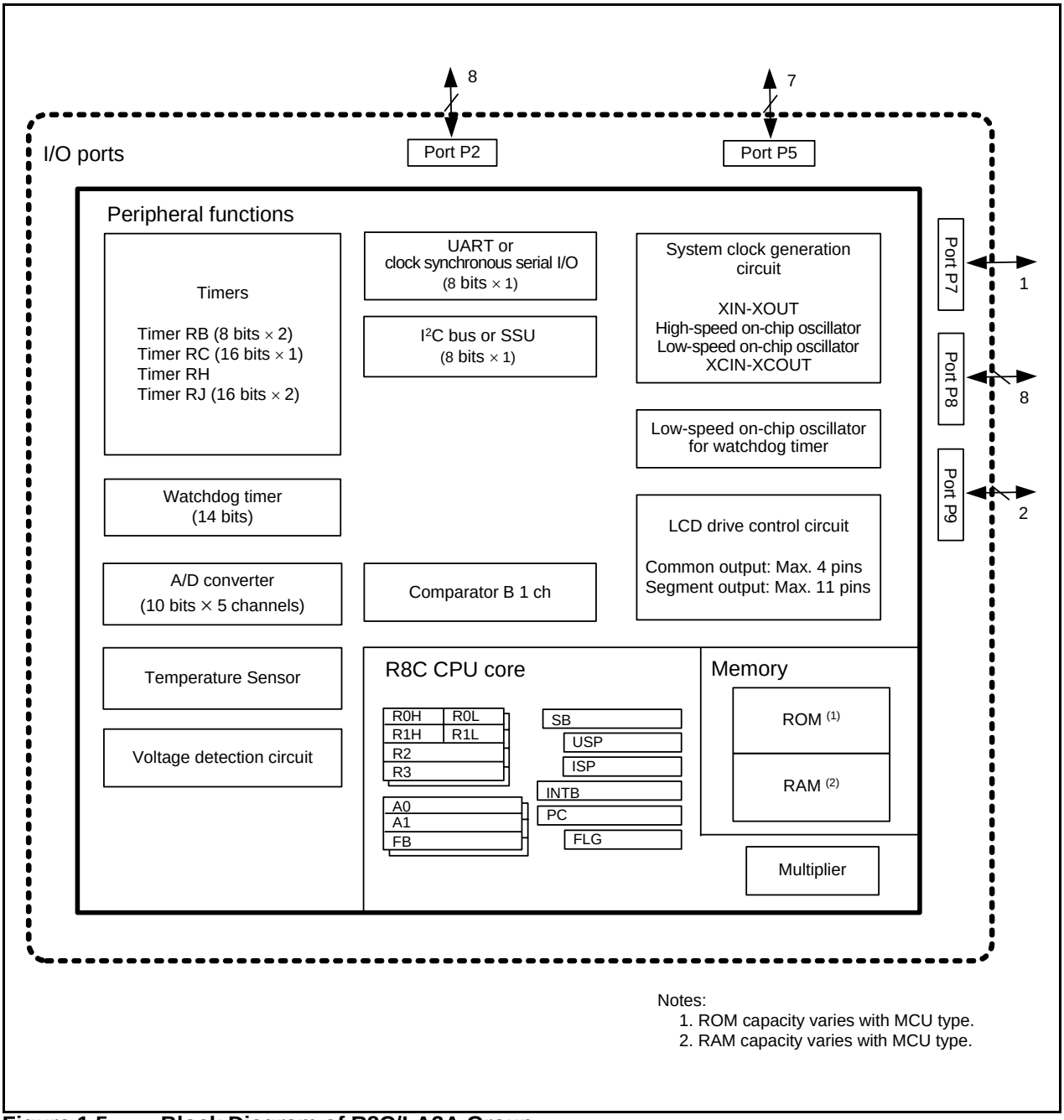


Figure 1.5 Block Diagram of R8C/LA3A Group

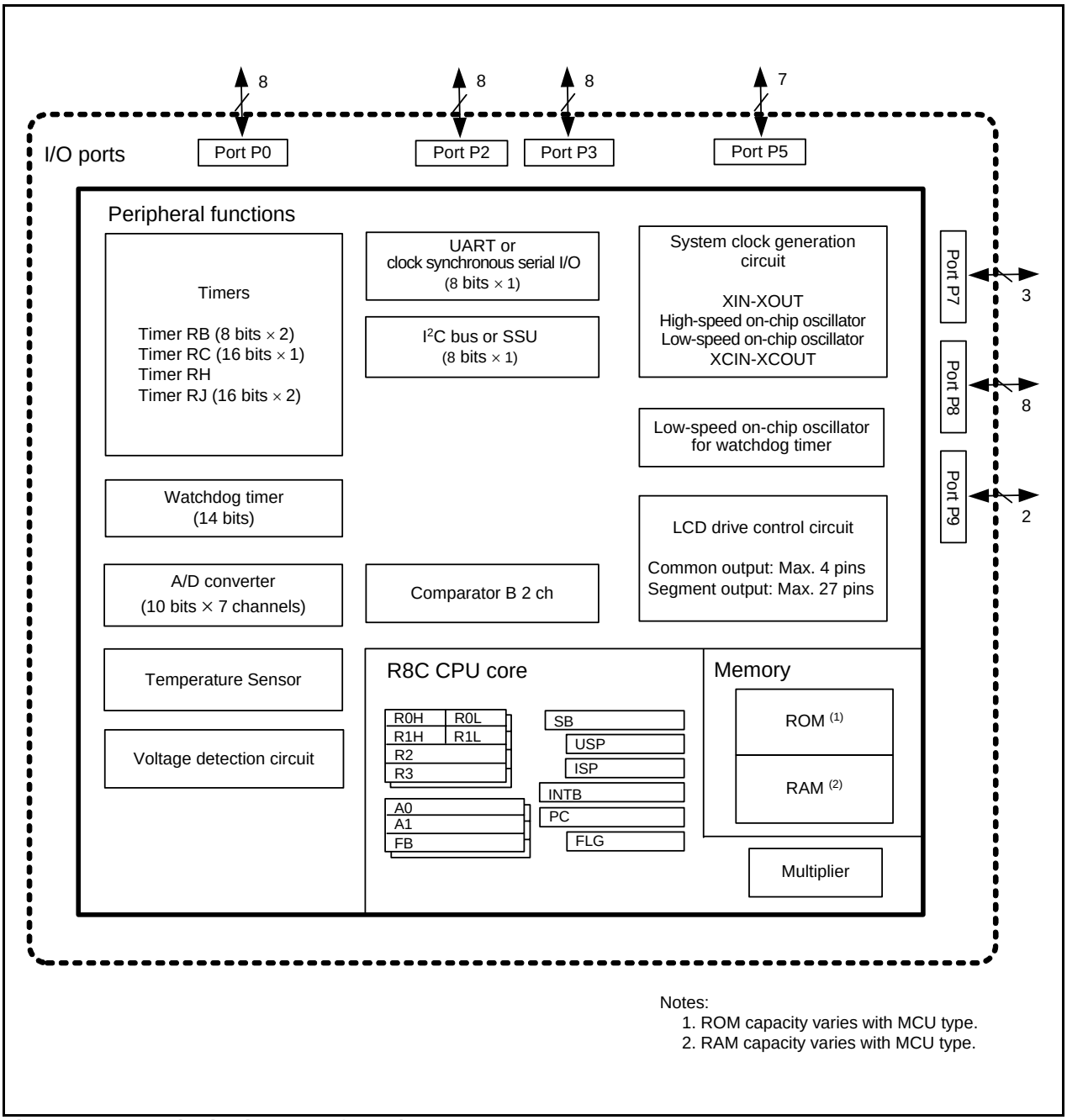


Figure 1.6 Block Diagram of R8C/LA5A Group

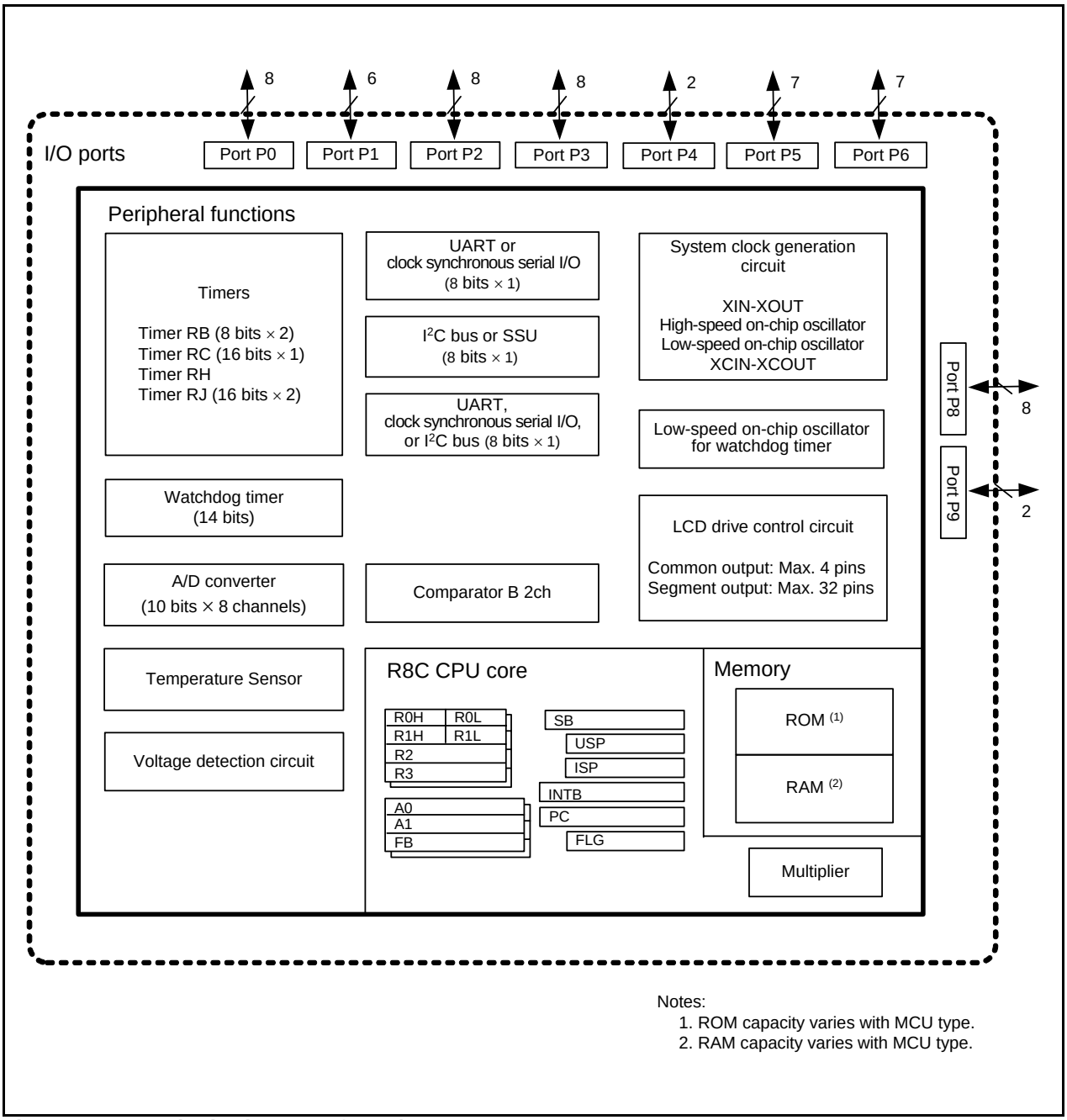
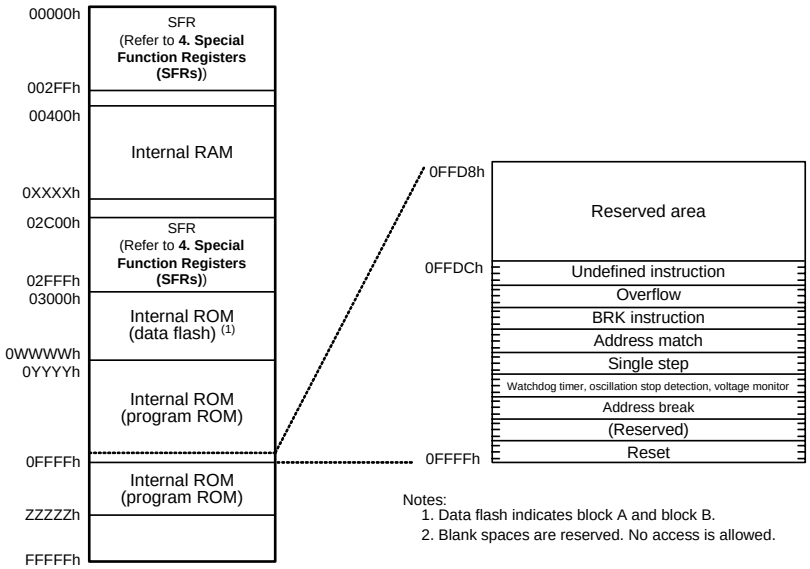


Figure 1.7 Block Diagram of R8C/LA6A Group

3. Memory

Figure 3.1 shows a Memory Map of each group. Each group has a 1-Mbyte address space from addresses 00000h to FFFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated higher addresses, beginning with address 03000h.
For example, two 1-Kbyte internal ROM (data flash) areas are allocated addresses 03000h to 037FFh. Two 2-Kbyte internal RAM (data flash) areas are allocated addresses 03000h to 03FFFh.
The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 3.5-Kbyte internal RAM area is allocated addresses 00400h to 011FFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh. Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.



Notes:
1. Data flash indicates block A and block B.
2. Blank spaces are reserved. No access is allowed.

Part Number	Internal ROM			Internal RAM		Data Flash	
	Capacity	Address 0YYYYh	Address ZZZZZh	Capacity	Address 0XXXXh	Capacity	Address 0WWWWh
R5F2LA32ANFP, R5F2LA32ADFP, R5F2LA52ANFP, R5F2LA52ADFP	8 Kbytes	0E000h	0FFFFh	2 Kbytes	00BFFh	1 Kbyte × 2	037FFh
R5F2LA34ANFP, R5F2LA34ADFP, R5F2LA54ANFP, R5F2LA54ADFP, R5F2LA64ANFP, R5F2LA64ANFA, R5F2LA64ADFP, R5F2LA64ADFA, R5F2LA84ANFP, R5F2LA84ANFA, R5F2LA84ADFP, R5F2LA84ADFA	16 Kbytes	0C000h	0FFFFh	2 Kbytes	00BFFh		
R5F2LA36ANFP, R5F2LA36ADFP, R5F2LA56ANFP, R5F2LA56ADFP, R5F2LA66ANFP, R5F2LA66ANFA, R5F2LA66ADFP, R5F2LA66ADFA, R5F2LA86ANFP, R5F2LA86ANFA, R5F2LA86ADFP, R5F2LA86ADFA	32 Kbytes	08000h	0FFFFh	2 Kbytes	00BFFh		
R5F2LA67ANFP, R5F2LA67ANFA, R5F2LA67ADFP, R5F2LA67ADFA, R5F2LA87ANFP, R5F2LA87ANFA, R5F2LA87ADFP, R5F2LA87ADFA	48 Kbytes	04000h	0FFFFh	3.5 Kbytes	011FFh		
R5F2LA38ANFP, R5F2LA38ADFP, R5F2LA58ANFP, R5F2LA58ADFP, R5F2LA68ANFP, R5F2LA68ANFA, R5F2LA68ADFP, R5F2LA68ADFA, R5F2LA88ANFP, R5F2LA88ANFA, R5F2LA88ADFP, R5F2LA88ADFA	64 Kbytes	04000h	13FFFh	3.5 Kbytes	011FFh		
R5F2LA6AANFP, R5F2LA6AANFA, R5F2LA6CADFP, R5F2LA6CADFA, R5F2LA8AANFP, R5F2LA8AANFA, R5F2LA8CADFP, R5F2LA8CADFA	96 Kbytes	04000h	1BFFFh	5.5 Kbytes	019FFh	2 Kbytes × 2	03FFFh
R5F2LA6AANFP, R5F2LA6AANFA, R5F2LA6CADFP, R5F2LA6CADFA, R5F2LA8AANFP, R5F2LA8AANFA, R5F2LA8CADFP, R5F2LA8CADFA	128 Kbytes	04000h	23FFFh	5.5 Kbytes	019FFh		

Figure 3.1 Memory Map

Table 4.9 SFR Information for R8C/LA5A Group (9) (1)

Address	Register	Symbol	After Reset
0200h	LCD Control Register	LCR0	00h
0201h			
0202h	LCD Option Clock Control Register	LCR2	00h
0203h	LCD Clock Control Register	LCR3	00h
0204h	LCD Display Control Register	LCR4	00h
0205h			
0206h	LCD Port Select Register 0	LSE0	00h
0207h	LCD Port Select Register 1	LSE1	00h
0208h	LCD Port Select Register 2	LSE2	00h
0209h			
020Ah			
020Bh	LCD Port Select Register 5	LSE5	00h
020Ch			
020Dh			
020Eh			
020Fh			
0210h	LCD Display Data Register	LRA0L	XXh
0211h		LRA1L	XXh
0212h		LRA2L	XXh
0213h		LRA3L	XXh
0214h		LRA4L	XXh
0215h		LRA5L	XXh
0216h		LRA6L	XXh
0217h		LRA7L	XXh
0218h		LRA8L	XXh
0219h		LRA9L	XXh
021Ah		LRA10L	XXh
021Bh		LRA11L	XXh
021Ch		LRA12L	XXh
021Dh		LRA13L	XXh
021Eh		LRA14L	XXh
021Fh		LRA15L	XXh
0220h		LRA16L	XXh
0221h		LRA17L	XXh
0222h		LRA18L	XXh
0223h		LRA19L	XXh
0224h		LRA20L	XXh
0225h		LRA21L	XXh
0226h		LRA22L	XXh
0227h		LRA23L	XXh
0228h		LRA24L	XXh
0229h		LRA25L	XXh
022Ah		LRA26L	XXh
022Bh			
022Ch			
022Dh			
022Eh			
022Fh			
0230h			
0231h			
0232h			
0233h			
0234h			
0235h			
0236h			
0237h			
:			
2FFFh			

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.12 SFR Information for R8C/LA8A Group (3) (1)

Address	Register	Symbol	After Reset
0080h	Timer RJ0 Control Register	TRJ0CR	00h
0081h	Timer RJ0 I/O Control Register	TRJ0IOC	00h
0082h	Timer RJ0 Mode Register	TRJ0MR	00h
0083h	Timer RJ0 Event Pin Select Register	TRJ0ISR	00h
0084h	Timer RJ0 Register	TRJ0	FFh
0085h			FFh
0086h			
0087h			
0088h	Timer RJ1 Control Register	TRJ1CR	00h
0089h	Timer RJ1 I/O Control Register	TRJ1IOC	00h
008Ah	Timer RJ1 Mode Register	TRJ1MR	00h
008Bh	Timer RJ1 Event Pin Select Register	TRJ1ISR	00h
008Ch	Timer RJ1 Register	TRJ1	FFh
008Dh			FFh
008Eh			
008Fh			
0090h	Timer RJ2 Control Register	TRJ2CR	00h
0091h	Timer RJ2 I/O Control Register	TRJ2IOC	00h
0092h	Timer RJ2 Mode Register	TRJ2MR	00h
0093h	Timer RJ2 Event Pin Select Register	TRJ2ISR	00h
0094h	Timer RJ2 Register	TRJ2	FFh
0095h			FFh
0096h			
0097h			
0098h	Timer RB1 Control Register	TRB1CR	00h
0099h	Timer RB1 One-Shot Control Register	TRB1OCR	00h
009Ah	Timer RB1 I/O Control Register	TRB1IOC	00h
009Bh	Timer RB1 Mode Register	TRB1MR	00h
009Ch	Timer RB1 Prescaler Register	TRB1PRE	FFh
009Dh	Timer RB1 Secondary Register	TRB1SC	FFh
009Eh	Timer RB1 Primary Register	TRB1PR	FFh
009Fh			
00A0h	UART0 Transmit/Receive Mode Register	U0MR	00h
00A1h	UART0 Bit Rate Register	U0BRG	XXh
00A2h	UART0 Transmit Buffer Register	U0TB	XXh
00A3h			XXh
00A4h	UART0 Transmit/Receive Control Register 0	U0C0	00001000b
00A5h	UART0 Transmit/Receive Control Register 1	U0C1	00000010b
00A6h	UART0 Receive Buffer Register	U0RB	XXh
00A7h			XXh
00A8h	UART2 Transmit/Receive Mode Register	U2MR	00h
00A9h	UART2 Bit Rate Register	U2BRG	XXh
00AAh	UART2 Transmit Buffer Register	U2TB	XXh
00ABh			XXh
00ACh	UART2 Transmit/Receive Control Register 0	U2C0	00001000b
00ADh	UART2 Transmit/Receive Control Register 1	U2C1	00000010b
00AEh	UART2 Receive Buffer Register	U2RB	XXh
00AFh			XXh
00B0h	UART2 Digital Filter Function Select Register	URXDF	00h
00B1h			
00B2h			
00B3h			
00B4h			
00B5h			
00B6h			
00B7h			
00B8h			
00B9h			
00BAh			
00BBh	UART2 Special Mode Register 5	U2SMR5	00h
00BCh	UART2 Special Mode Register 4	U2SMR4	00h
00BDh	UART2 Special Mode Register 3	U2SMR3	000X0X0Xb
00BEh	UART2 Special Mode Register 2	U2SMR2	X0000000b
00BFh	UART2 Special Mode Register	U2SMR	X0000000b

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.13 SFR Information for R8C/LA8A Group (4) (1)

Address	Register	Symbol	After Reset
00C0h	A/D Register 0	AD0	XXh
00C1h			000000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			000000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh			000000XXb
00CCh	A/D Register 6	AD6	XXh
00CDh			000000XXb
00CEh	A/D Register 7	AD7	XXh
00CFh			000000XXb
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Mode Register	ADMOD	00h
00D5h	A/D Input Select Register	ADINSEL	11000000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh	A/D Control Register 2	ADCON2	00h
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h	Port P5 Register	P5	XXh
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh	Port P6 Register	P6	XXh
00EDh	Port P7 Register	P7	XXh
00EEh	Port P6 Direction Register	PD6	00h
00EFh	Port P7 Direction Register	PD7	00h
00F0h	Port P8 Register	P8	XXh
00F1h	Port P9 Register	P9	XXh
00F2h	Port P8 Direction Register	PD8	00h
00F3h	Port P9 Direction Register	PD9	00h
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.19 ID Code Areas and Option Function Select Area

Address	Area Name	Symbol	After Reset
:			
FFDBh	Option Function Select Register 2	OFS2	(Note 1)
:			
FFDFh	ID1		(Note 2)
:			
FFE3h	ID2		(Note 2)
:			
FFEBh	ID3		(Note 2)
:			
FFEFh	ID4		(Note 2)
:			
FFF3h	ID5		(Note 2)
:			
FFF7h	ID6		(Note 2)
:			
FFFBh	ID7		(Note 2)
:			
FFFFh	Option Function Select Register	OFS	(Note 1)

Notes:
1. The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not write additions to the option function select area. If the block including the option function select area is erased, the option function select area is set to FFh.
   When blank products are shipped, the option function select area is set to FFh. It is set to the written value after written by the user.
   When factory-programming products are shipped, the value of the option function select area is the value programmed by the user.
2. The ID code areas are allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not write additions to the ID code areas. If the block including the ID code areas is erased, the ID code areas are set to FFh.
   When blank products are shipped, the ID code areas are set to FFh. They are set to the written value after written by the user.
   When factory-programming products are shipped, the value of the ID code areas is the value programmed by the user.

Table 5.7 Flash Memory (Program ROM) Characteristics
(V_{CC} = 1.8 to 5.5 V and T_{opr} = 0 to 60 °C, unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance (1)		10,000 (2)	–	–	times
–	Byte program time		–	80	–	µs
–	Block erase time		–	0.12	–	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		–	–	0.25 + CPU clock × 3 cycles	ms
–	Time from suspend until erase restart		–	–	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		–	–	30 + CPU clock × 1 cycle	µs
–	Program, erase voltage		1.8	–	5.5	V
–	Read voltage		1.8	–	5.5	V
–	Program, erase temperature		0	–	60	°C
–	Data hold time (6)	Ambient temperature = 85 °C	10	–	–	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.19 DC Characteristics (2) [4.0 V ≤ Vcc ≤ 5.5 V]
(Topr = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Condition								Standard			Unit
			Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ. (3)	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	–		–	4.7	10	mA
			16 MHz	Off	Off	125 kHz	No division	–		–	3.9	8	mA
			10 MHz	Off	Off	125 kHz	No division	–		–	2.3	–	mA
			20 MHz	Off	Off	Off	No division	FMR27 = 1 MSTCR0 = BEh MSTCR1 = 3Fh	Flash memory off Program operation on RAM Module standby setting enabled	–	3.1	–	mA
			20 MHz	Off	Off	125 kHz	Divide-by-8	–		–	1.8	–	mA
			16 MHz	Off	Off	125 kHz	Divide-by-8	–		–	1.5	–	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	–		–	1.0	–	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz	125 kHz	No division	–		–	5.0	11	mA
			Off	Off	20 MHz	125 kHz	Divide-by-8	–		–	2.1	–	mA
			Off	Off	4 MHz	125 kHz	Divide-by-16	MSTCR0 = BEh MSTCR1 = 3Fh		–	0.9	–	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	No division	FMR27 = 1 VCA20 = 0		–	110	320	µA
			Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0		–	63	220	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0		–	60	220	µA
			Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM	–	46	–	µA
		Wait mode	Off	Off	Off	125 kHz	–	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation	–	9.0	50	µA
			Off	Off	Off	125 kHz	–	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off	–	2.8	33	µA
			Off	32 kHz	Off	Off	–	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed Peripheral clock off Timer RH operation in real-time clock mode LCD drive control circuit (4) When external division resistors are used	–	4.6	–	µA
			Off	32 kHz	Off	Off	–	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RH operation in real-time clock mode	–	2.4	–	µA
		Stop mode	Off	Off	Off	Off	–	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25 °C Peripheral clock off	–	0.5	2.2	µA
			Off	Off	Off	Off	–	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85 °C Peripheral clock off	–	1.2	–	µA
		Power-off mode	Off	Off	Off	Off	–	–	Power-off 0 Topr = 25 °C	–	0.01	0.1	µA
			Off	Off	Off	Off	–	–	Power-off 0 Topr = 85 °C	–	0.03	–	µA
			Off	32 kHz	Off	Off	–	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Power-off 2 Topr = 25 °C	–	1.8	6.4	µA
			Off	32 kHz	Off	Off	–	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Power-off 2 Topr = 85 °C	–	2.7	–	µA

Notes:
1. Vcc = 4.0 V to 5.5 V, single chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. Vcc = 5.0 V
4. VLCD = Vcc, external division resistors are used for VL3 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG26 are selected, and segment and common output pins are open. The standard value does not include the current that flows through external division resistors.

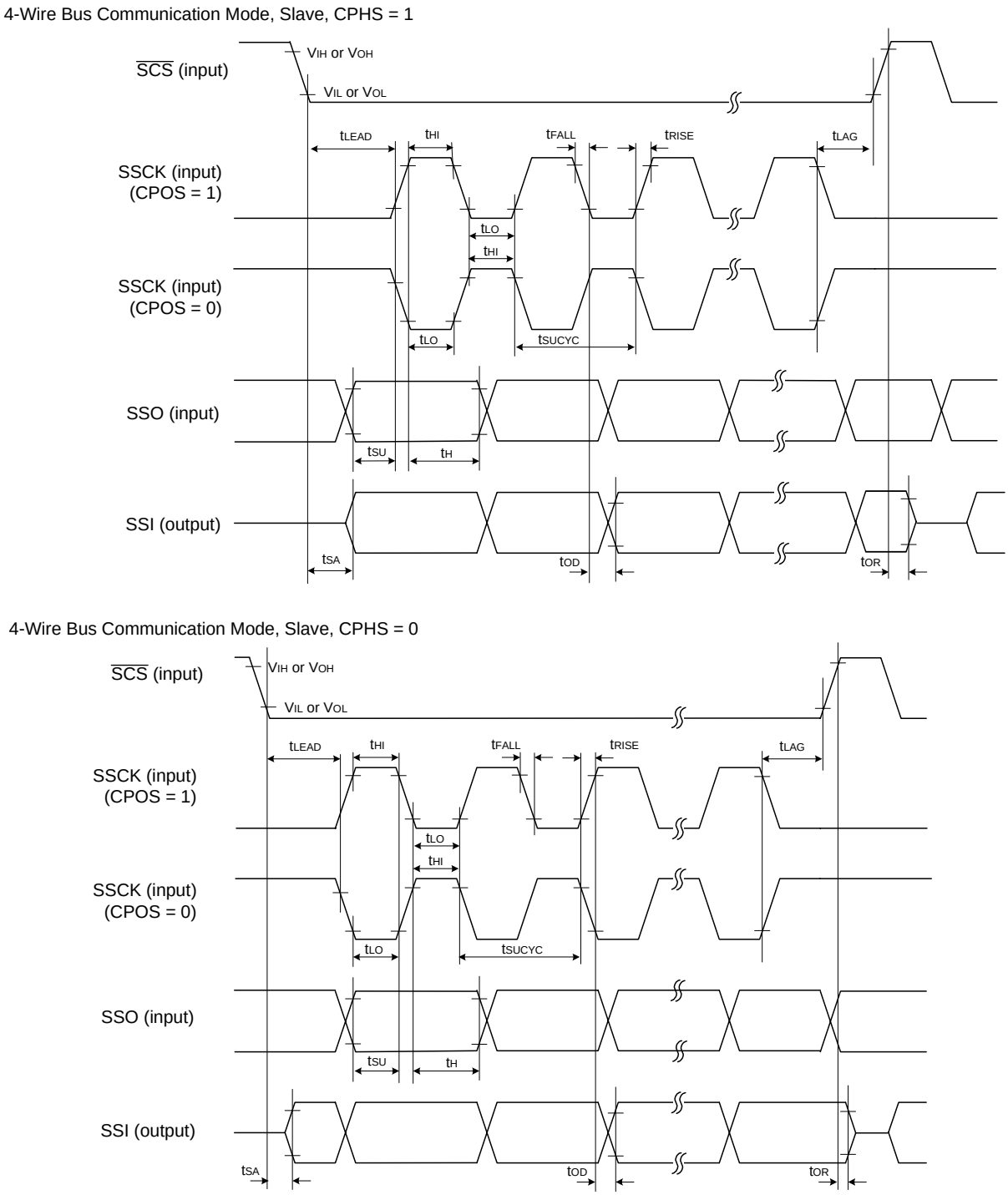


Figure 5.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)

Table 5.26 Timing Requirements of External Clock Input (XIN, XCIN)
(Vss = 0 V and Topr = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2V, Topr = 25°C		Vcc = 3V, Topr = 25°C		Vcc = 5V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	200	–	50	–	50	–	ns
$t_{WH(XIN)}$	XIN input “H” width	90	–	24	–	24	–	ns
$t_{WL(XIN)}$	XIN input “L” width	90	–	24	–	24	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	20	–	20	–	20	–	µs
$t_{WH(XCIN)}$	XCIN input “H” width	10	–	10	–	10	–	µs
$t_{WL(XCIN)}$	XCIN input “L” width	10	–	10	–	10	–	µs

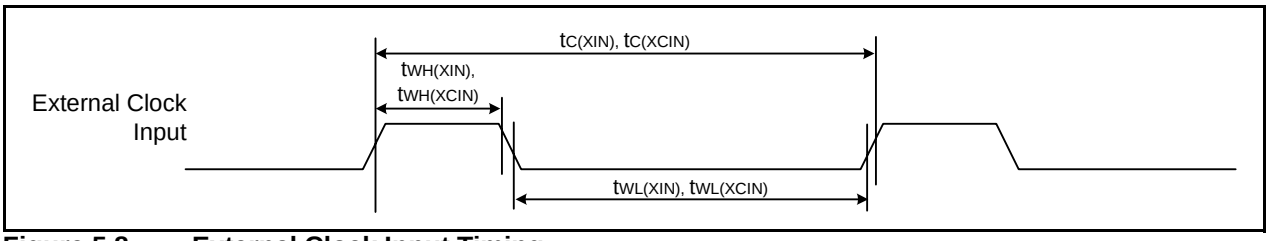


Figure 5.8 External Clock Input Timing

Table 5.27 Timing Requirements of TRJiIO (i = 0 or 1)
(Vss = 0 V and Topr = –20 to 85 °C (N version)/ –40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2V, Topr = 25°C		Vcc = 3V, Topr = 25°C		Vcc = 5V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(TRJIO)}$	TRJiIO input cycle time	500	–	300	–	100	–	ns
$t_{WH(TRJIO)}$	TRJiIO input “H” width	200	–	120	–	40	–	ns
$t_{WL(TRJIO)}$	TRJiIO input “L” width	200	–	120	–	40	–	ns

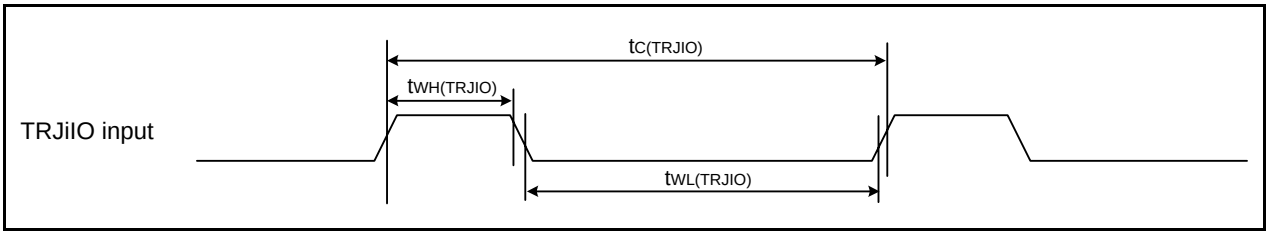


Figure 5.9 Input Timing of TRJiIO

5.2.2 Recommended Operating Conditions

Table 5.31 Recommended Operating Conditions
(Vcc = 1.8 to 5.5 V and Topr = −20 to 85°C (N version)/ −40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter				Conditions	Standard			Unit
						Min.	Typ.	Max.	
Vcc/AVcc	Supply voltage					1.8	–	5.5	V
Vss/AVss	Supply voltage					–	0	–	V
VIH	Input “H” voltage	Other than CMOS input			4.0 V ≤ Vcc ≤ 5.5 V	0.8 Vcc	–	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.8 Vcc	–	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.9 Vcc	–	Vcc	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0.5 Vcc	–	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.55 Vcc	–	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.65 Vcc	–	Vcc	V
				Input level selection : 0.5 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0.65 Vcc	–	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.7 Vcc	–	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.8 Vcc	–	Vcc	V
				Input level selection : 0.7 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0.85 Vcc	–	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.85 Vcc	–	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.85 Vcc	–	Vcc	V
VIL	Input “L” voltage	Other than CMOS input			4.0 V ≤ Vcc ≤ 5.5 V	0	–	0.2 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	–	0.2 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	–	0.05 Vcc	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0	–	0.2 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	–	0.2 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	–	0.2 Vcc	V
				Input level selection : 0.5 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0	–	0.4 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	–	0.3 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	–	0.2 Vcc	V
				Input level selection : 0.7 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0	–	0.55 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	–	0.45 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	–	0.35 Vcc	V
IOH(sum)	Peak sum output “H” current	Sum of all pins IOH(peak)				–	–	−160	mA
IOH(sum)	Average sum output “H” current	Sum of all pins IOH(avg)				–	–	−80	mA
IOH(peak)	Peak output “H” current	Port P7_0, P7_1, P8 (2)				–	–	−40	mA
		Other pins				–	–	−10	mA
IOH(avg)	Average output “H” current (1)	Port P7_0, P7_1, P8 (2)				–	–	−20	mA
		Other pins				–	–	−5	mA
IOL(sum)	Peak sum output “L” current	Sum of all pins IOL(peak)				–	–	160	mA
IOL(sum)	Average sum output “L” current	Sum of all pins IOL(avg)				–	–	80	mA
IOL(peak)	Peak output “L” current	Port P7_0, P7_1, P8 (2)				–	–	40	mA
		Other pins				–	–	10	mA
IOL(avg)	Average output “L” current (1)	Port P7_0, P7_1, P8 (2)				–	–	20	mA
		Other pins				–	–	5	mA
f(XIN)	XIN clock input oscillation frequency				2.7 V ≤ Vcc ≤ 5.5 V	2	–	20	MHz
					1.8 V ≤ Vcc < 2.7 V	2	–	8	MHz
f(XCIN)	XCIN oscillation frequency				1.8 V ≤ Vcc ≤ 5.5 V	–	32.768	–	kHz
	XCIN external clock input frequency				1.8 V ≤ Vcc ≤ 5.5 V	–	–	50	kHz
fOCO20M	When used as the count source for timer RC (3)				2.7 V ≤ Vcc ≤ 5.5 V	18.432	–	20	MHz
fOCO-F	fOCO-F frequency				2.7 V ≤ Vcc ≤ 5.5 V	-	-	20	MHz
					1.8 V ≤ Vcc < 2.7 V	-	-	8	MHz
–	System clock frequency				2.7 V ≤ Vcc ≤ 5.5 V	-	-	20	MHz
					1.8 V ≤ Vcc < 2.7 V	-	-	8	MHz
f(BCLK)	CPU clock frequency				2.7 V ≤ Vcc ≤ 5.5 V	0	-	20	MHz
					1.8 V ≤ Vcc < 2.7 V	0	-	8	MHz

Notes:
1. The average output current indicates the average value of current measured during 100 ms.
2. This applies when the drive capacity of the output transistor is set to High by registers P7DRR and P8DRR. When the drive capacity is set to Low, the value of any other pin applies.
3. fOCO20M can be used as the count source for timer RC in the range of Vcc = 2.7 V to 5.5V.

5.2.3 Peripheral Function Characteristics

Table 5.32 A/D Converter Characteristics
(Vcc/AVcc = Vref = 1.8 to 5.5 V, Vss = 0 V, and Topr = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
–	Resolution		Vref = AVcc		–	–	10	Bit
–	Absolute accuracy (2)	10-bit mode	Vref = AVcc = 5.0 V	AN0 to AN11 input	–	–	±3	LSB
			Vref = AVcc = 2.2 V	AN0 to AN11 input	–	–	±5	LSB
			Vref = AVcc = 1.8 V	AN0 to AN11 input	–	–	±5	LSB
		8-bit mode	Vref = AVcc = 5.0 V	AN0 to AN11 input	–	–	±2	LSB
			Vref = AVcc = 2.2 V	AN0 to AN11 input	–	–	±2	LSB
			Vref = AVcc = 1.8 V	AN0 to AN11 input	–	–	±2	LSB
ϕAD	A/D conversion clock		4.0 ≤ Vref = AVcc ≤ 5.5 V (1)		1	–	20	MHz
			3.2 ≤ Vref = AVcc ≤ 5.5 V (1)		1	–	16	MHz
			2.7 ≤ Vref = AVcc ≤ 5.5 V (1)		1	–	10	MHz
			1.8 ≤ Vref = AVcc ≤ 5.5 V (1)		1	–	8	MHz
–	Tolerance level impedance				–	3	–	kΩ
tCONV	Conversion time	10-bit mode	Vref = AVcc = 5.0 V, ϕAD = 20 MHz		2.2	–	–	µs
		8-bit mode	Vref = AVcc = 5.0 V, ϕAD = 20 MHz		2.2	–	–	ms
tSAMP	Sampling time		ϕAD = 20 MHz		0.8	–	–	µs
IVref	Vref current		Vcc = 5 V, XIN = f1 = ϕAD = 20 MHz		-	45	–	µA
Vref	Reference voltage				1.8	–	AVcc	V
VIA	Analog input voltage (3)				0	–	Vref	V
OCVREF	On-chip reference voltage		2 MHz ≤ ϕAD ≤ 4 MHz		1.53	1.70	1.87	V

Notes:
1. The A/D conversion result will be undefined in wait mode, stop mode, power-off mode, when the flash memory stops, and in low-current-consumption mode. Do not perform A/D conversion in these states or transition to these states during A/D conversion.
2. This applies when the peripheral functions are stopped.
3. When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

Table 5.33 Temperature Sensor Characteristics
(VSS = 0 V and Topr = –20 to 85 °C (N version)/–40 to 85 °C (D version), unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
VTMP	Temperature sensor output voltage	1.8 V ≤ Vref = AVcc ≤ 5.5 V ϕAD = 1.0 MHz to 5.0 MHz Ambient temperature = 25 °C	550	600	650	mV
–	Temperature coefficient	1.8 V ≤ Vref = AVcc ≤ 5.5 V ϕAD = 1.0 MHz to 5.0 MHz Ambient temperature = 25 °C	–	–2.1	–	mV/°C
–	Start-up time	1.8 V ≤ Vref = AVcc ≤ 5.5 V ϕAD = 1.0 MHz to 5.0 MHz	–	–	200	µs
ITMP	Operating current	1.8 V ≤ Vref = AVcc ≤ 5.5 V ϕAD = 1.0 MHz to 5.0 MHz	–	100	–	µA

Table 5.49 DC Characteristics (3) [2.7 V ≤ Vcc < 4.0 V]
(Topr = –20 to 85°C (N version)/ –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output “H” voltage		Port P7_0, P7_1, P8 (1)	I_{OH} = –5 mA	V_{CC} – 0.5	–	V_{CC}	V
			Other pins	I_{OH} = –1 mA	V_{CC} – 0.5	–	V_{CC}	V
V_{OL}	Output “L” voltage		Port P7_0, P7_1, P8 (1)	I_{OL} = 5 mA	–	–	0.5	V
			Other pins	I_{OL} = 1 mA	–	–	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{INT4}$, INT5, $\overline{INT6}$, $\overline{INT7}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, KI4, KI5, KI6, KI7, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRJ0IO, TRJ1IO, TRJ2IO, $\overline{TRCTRG}$, TRCCLK, $\overline{ADTRG}$, RXD0, RXD2, CLK0, CLK2, SSI, SCL, SDA, SSO			0.05	0.4	–	V
		$\overline{RESET}$, $\overline{WKUP0}$			0.1	0.8	–	V
I_{IH}	Input “H” current		VI = 3 V, V_{CC} = 3 V		–	–	5.0	µA
I_{IL}	Input “L” current		VI = 0 V, V_{CC} = 3 V		–	–	–5.0	µA
R_{PULLUP}	Pull-up resistance		VI = 0 V, V_{CC} = 3 V		25	80	140	kΩ
R_{fXIN}	Feedback resistance	XIN			–	2.0	–	MΩ
R_{fXCIN}	Feedback resistance	XCIN			–	14	–	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	–	–	V

Note:
1. This applies when the drive capacity of the output transistor is set to High by registers P7DRR and P8DRR. When the drive capacity is set to Low, the value of any other pin applies.

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